

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
21 December 2006 (21.12.2006)

PCT

(10) International Publication Number
WO 2006/134217 A1

(51) International Patent Classification:

H05K 1/00 (2006.01) *H05K 3/42* (2006.01)
H05K 1/11 (2006.01) *H05K 3/46* (2006.01)

(21) International Application Number:

PCT/FI2006/000208

(22) International Filing Date: 15 June 2006 (15.06.2006)

(25) Filing Language:

Finnish

(26) Publication Language:

English

(30) Priority Data:

20050645 16 June 2005 (16.06.2005) FI

(71) Applicant (for all designated States except US): **IMBERA ELECTRONICS OY** [FI/FI]; P.O. Box 74, FI-02151 Espoo (FI).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **TUOMINEN, Risto** [FI/FI]; Väinölänkatu 17 B 18, FI-00610 Helsinki (FI). **IIHOLA, Antti** [FI/FI]; Koskelantie 33 A 5, FI-00610 Helsinki (FI). **PALM, Petteri** [FI/FI]; Alkutie 47 as. 1, FI-00660 Helsinki (FI).

(74) Agent: **SEPPO LAINE OY**; Itämerenkatu 3 B, FI-00180 Helsinki (FI).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

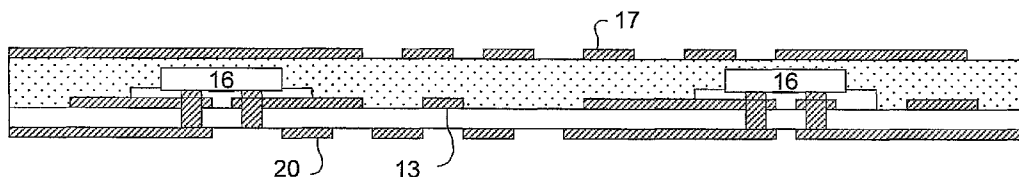
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD FOR MANUFACTURING A CIRCUIT BOARD STRUCTURE, AND A CIRCUIT BOARD STRUCTURE



(57) Abstract: This publication discloses a method for manufacturing a circuit-board structure. According to the method, a conductor pattern (13) is made, and contact openings are made in it for a component's (16) electrical contacts. After this, the component (16) is attached relative to the conductor pattern (13), in such a way that the contact areas or contact bumps of the component lie next to the contact openings. After this, an electrically conductive material is introduced to the contact openings, in order to form electrical contacts between the conductor pattern (13) and the component (16).

WO 2006/134217 A1